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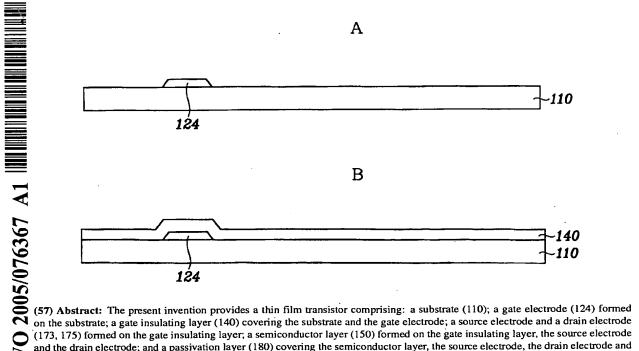
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- (71) Applicant (for all designated States except US): SAM-SUNG ELECTRONICS CO., LTD. [KR/KR]; 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, 442-742 (KR).
- (72) Inventors: and
- (75) Inventors/Applicants (for US only): RYU, Min-Seong [KR/KR]; Shinnamusil Jugong 5-danji Apt. 514-1602, Yeongtong-dong, Paldal-gu, Suwon-si, Gyeonggi-do 442-727 (KR). LEE, Yong-Uk [KR/KR]; Yaksu Apt.

309, Jung-dong, Jungwon-gu, Seongnam-si, Gyonggi-do, 464-896 (KR). CHOI, Tae-Young [KR/KR]; 301, 122-670, Jegi-dong, Dongdaemun-gu, Seoul 130-060 (KR). KIM, Bo-Sung [KR/KR]; 20th Fl, 474-20, Bangbae 2-dong, Seocho-gu, Seoul 137-819 (KR).

- (74) Agent: YOU ME PATENT AND LAW FIRM; Seolim Bldg., 649-10, Yoksam-dong, Kangnam-ku, Seoul 135-080 (KR).
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(54) Title: THIN FILM TRANSISTOR ARRAY PANEL AND MANUFACTURING METHOD THEREOF



(173, 175) formed on the gate insulating layer, a semiconductor layer (150) formed on the gate insulating layer, the source electrode and the drain electrode; and a passivation layer (180) covering the semiconductor layer, the source electrode, the drain electrode and the gate insulating layer, wherein at least one of the gate insulating layer and the passivation layer is made of Parylene.

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